

# Golden List of Reviewers for 2019

First Name	Last Name	Affiliation	Country
C. K.	Aanandan	Cochin University of Science and Technology	India
Sanjar	Abrarov	York University	Canada
Gina	Adam	University of California, Santa Barbara	United States
Ashish	Agrawal	Intel	United States
Harshit	Agarwal	University of California, Berkeley	United States
Rajesh	Agarwal	SRM University	India
Zeshan	Ahmad	University of Texas at Dallas	United States
Elaheh	Ahmadi	University of Michigan	United States
Ali	Ahmadi Peyghan	Islamic Azad University	Iran
Karim	Ahmed	National University of Singapore	Singapore
Khaled	Ahmed	Intel	United States
Sujin	Ahn	Samsung Electronics Co. Ltd.	Korea
Arman	Ahnood	University of Melbourne	Australia
Ayayi	Ahyi	Auburn University	United States
Arjun	Ajaykumar	IMEC	Belgium
Ozgur	Aktas	Avogy	United States
John	Albrecht	Michigan State University	United States
Aleksandar	Aleksov	Intel	United States
Giovanni	Alfieri	ABB Corporate Research Center	Switzerland
Abdullah	Alhassan	University of California, Santa Barbara	United States
Tarek	Ali	Fraunhofer-Center Nanoelektronische Technologien	Germany
Asaad	Al-mashaal	University of Edinburgh	United Kingdom
Fabien	Ambriz-Vargas	INRS	Canada
Mahdi	Aminian	University of Guilan	Iran
Salvatore	Amoroso	Synopsys Inc.	United Kingdom
Frédéric	André	Thales Electron Devices	France
Simon	Ang	University of Arkansas	United States
Jin-Ping	Ao	University of Tokushima	Japan
Andrea	Arias	Teledyne Scientific and Imaging	United States
Gokhan	Atmaca	CEA LETI	France
Victor	Atuchin	Rzhanov Institute of Semiconductor Physics, SB RAS	Russia
Zubair	Azim	Intel	United States
Ahmedullah	Aziz	Purdue University	United States
Giorgio	Baccarani	Università di Bologna	Italy
Michael	Bachmann	Ketek GmbH	Germany
Samuel	Bader	Cornell University	United States
Woorham	Bae	University of California, Berkeley	United States
Eldad	Bahat Treidel	Ferdinand-Braun-Institut für Höchstfrequenztechnik	Germany
Behraad	Bahreyni	Simon Fraser University	Canada
Benoit	Bakeroot	IMEC, Ghent University	Belgium

First Name	Last Name	Affiliation	Country
Victor	Balderrama	CONACYT - Center for Engineering and Industrial Development (CIDESI),	Mexico
Francis	Balestra	IMEP-LAHC	France
Sujit	Banerjee	Monolith Semiconductor	United States
Wenzhong	Bao	Fudan University	China
Douglas	Barlage	University of Alberta	Canada
Sergey	Baryshev	Michigan State University	United States
Md Zunaid	Baten	Bangladesh University of Engineering and Technology	Bangladesh
Can	Bayram	University of Illinois at Urbana-Champaign	United States
Behdash	Behin-Aein	GlobalFoundries	United States
Federico	Bella	Politecnico di Torino	Italy
Philippe	Benech	G2ELab	France
Dan	Berco	Nanyang Technological University	Singapore
Paul	Berger	Ohio State University	United States
Juan Paolo	Bermundo	Nara Institute of Science and Technology	Japan
Gennadi	Bersuker	Aerospace Corp	United States
Cristina	Besleaga	National Institute of Materials Physics	Romania
Sonik	Bhatia	Kanya Maha Vidyalaya	India
Debanjan	Bhowmik	Indian Institute of Technology Delhi	India
Maruf	Bhuiyan	Yale University	United States
Krishna	Bhuwalka	Samsung Electronics Co. Ltd.	Korea
Madhur	Bobde	Alpha & Omega Semiconductor	United States
Joseph	Boisvert	Raytheon Co.	United States
Boni	Boksteen	ABB Semiconductors	Switzerland
Ageeth	Bol	IBM T.J. Watson Research Center	United States
Buddha Deka	Boruah	University of Cambridge	United Kingdom
Panagiotis	Bousoulas	National Technical University of Athens	Greece
Fabian	Bufler	IMEC	Belgium
Humberto	Campanella	GlobalFoundries	Singapore
Kerem	Camsari	Purdue University	United States
Giuseppe	Cantarella	Libera Università di Bolzano	Italy
Kurtis	Cantley	Boise State University	United States
Qing	Cao	University of Illinois at Urbana-Champaign	United States
Yu	Cao	Qorvo, Inc.	United States
Adrián	Carretero-Genevriér	CNRS	France
Cristian	Cassella	Northeastern University	United States
Giulia	Casula	Università Degli Studi di Cagliari	Italy
Antoniopio	Catalano	Università Degli Studi di Napoli Federico II	Italy
Roman	Caudillo	Intel	United States
Umberto	Celano	IMEC	Belgium
Eunjung	Cha	Chalmers Tekniska Hogskola	Sweden
Kelson	Chabak	US Air Force Research Laboratory	United States
Yang	Chai	Hong Kong Polytechnic University	Hong Kong
Zheng	Chai	Liverpool John Moores University	United Kingdom
Indranil	Chakraborty	Purdue University	United States
Partha	Chakraborty	CFD Research Corp	United States
Sudipta	Chakraborty	Macquarie University	Australia
Hareesh	Chandrasekar	University of Bristol	United Kingdom
Chih-Hung	Chang	Oregon State University	United States
Chih-Sheng	Chang	Taiwan Semiconductor Manufacturing Co. Ltd.	Taiwan
Sou-Chi	Chang	Georgia Institute of Technology	United States
Sung-Jae	Chang	Electronics and Telecommunications Research Institute	Korea
Ting-Chang	Chang	National Sun Yat-Sen University	Taiwan
Tzu-Hsuan	Chang	National Taiwan University	Taiwan

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Caitlin	Chapin	Stanford University	United States
Korok	Chatterjee	University of California, Berkeley	United States
Reet	Chaudhuri	Cornell University	United States
Rishu	Chaujar	Delhi Technological University	India
Albert	Chen	Intel	United States
Baoxing	Chen	Analog Devices Inc.	United States
Changqing	Chen	Huazhong University of Science and Technology,	China
Chen	Chen	Institute of Microelectronics, Chinese Academy of Sciences	China
Ian	Chen	Maxim Integrated	United States
Lung-Chien	Chen	National Taipei University of Technology	Taiwan
Po-Hsun	Chen	National Sun Yat-Sen University	Taiwan
Qianwen	Chen	IBM	United States
Ruqi	Chen	South China Agricultural University	China
Shuming	Chen	Southern University of Science and Technology	China
Si	Chen	Uppsala University	Sweden
Wenhao	Chen	Arizona State University	United States
Xiaodong	Chen	Nanyang Technological University	Singapore
Xiaodong	Chen	Queen Mary University of London	United Kingdom
Zhong	Chen	University of Arkansas	United States
Binjie	Cheng	Synopsys Inc.	United Kingdom
Yu-Ting	Cheng	National Chiao Tung University	Taiwan
Zhihui	Cheng	Duke University	United States
Ushe	Chipengo	ANSYS Inc.	United States
Hsien-Chin	Chiu	Chang Gung University	Taiwan
Sang June	Cho	University of Wisconsin-Madison	United States
Sung Haeng	Cho	Electronics and Telecommunications Research Institute	Korea
Woosung	Choi	Samsung Semiconductor, Inc.	United States
Chong Tow	Chong	Singapore University of Technology and Design	Singapore
Nadim	Chowdhury	Massachusetts Institute of Technology	United States
Sauvik	Chowdhury	ON Semiconductor	United States
Srabanti	Chowdhury	University of California, Davis	United States
Subhra	Chowdhury	Magnolia Optical Technologies, Inc.	United States
Jae-Hwan	Chu	University of California, Santa Barbara	United States
Rongming	Chu	Pennsylvania State University	United States
Yuanchen	Chu	Massachusetts Institute of Technology	United States
Beelee	Chua	Korea University	Korea
Kai-Hsin	Chuang	IMEC	Belgium
Seungjun	Chung	University of California, Berkeley	United States
Hugh	Churchill	University of Arkansas	United States
Florin	Ciubotaru	IMEC	Belgium
David	Clark	Raytheon Systems Limited	United Kingdom
Lorenzo	Colace	Università di Roma	Italy
Sergio	Colangeli	Università di Roma Tor Vergata	Italy
Daniel	Connelly	University of California, Berkeley	United States
Stefan	Cosemans	SureCore	Belgium
Marius	Costache	Catalan Institute of Nanoscience and Nanotechnology (ICN2)	Spain
Flavien	Cozette	3IT	Canada
Kevin	Crawford	US Army Research Laboratory	United States
Alessandro	Cresti	IMEP-LAHC	France
Fuccio	Cristiano	LAAS-CNRS	France
Rajendra	Dahal	Rensselaer Polytechnic Institute	United States
Tianjun	Dai	University of Electronic Science and Technology of China	China

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Alberto	Dalla Mora	Politecnico di Milano	Italy
Giang	Dang	Kochi University of Technology	Japan
Saptarshi	Das	Pennsylvania State University	United States
Suman	Das	Sikkim Manipal Institute of Technology	India
Avirup	Dasgupta	University of California, Berkeley	United States
Sudeb	Dasgupta	Indian Institute of Technology Roorkee	India
Tara	Dash	ITER, SOA University	India
Gijs	De Raad	NXP Semiconductors	Netherlands
Michelly	De Souza	Centro Universitario da FEI	Brazil
Bishwajit	Debnath	University of California, Riverside	United States
David	Deen	Naval Research Laboratory	United States
Vladislav	Demidov	Universität Münster	Germany
Sujay	Desai	Intel	United States
Sanchit	Deshmukh	Stanford University	United States
Veeresh Vidyadhar	Deshpande	IMEC	Belgium
Wouter	Devulder	IMEC	Belgium
Giorgio	Di Natale	Université de Montpellier	France
Luca	Di Piazza	IMEC	Belgium
Lili	Ding	Northwest Institute of Nuclear Technology	China
José	Diniz	Universidade Estadual de Campinas, Brazil	Brazil
Yingda	Dong	Micron Technology	United States
Zhipeng	Dong	Univeristy of Florida	United States
Wei	Dou	University of Arkansas	United States
Guo-Tong	Du	Jilin University	China
Sijun	Du	University of Cambridge	United Kingdom
Yuchen	Du	GlobalFoundries	United States
Ray	Duffy	Tyndall National Institute	Ireland
Maitreya	Dutta	Intel	United States
Satadal	Dutta	University of Twente	Netherlands
Sourav	Dutta	University of Notre Dame	United States
Mona	Ebrish	IBM Research	United States
Mattias	Ekström	KTH Royal Institute of Technology	Sweden
Khalil G.	El Hajjam	INL INSA Lyon	France
Karim	El Sayed	Synopsys Inc.	United States
Karim	Elgammal	KTH Royal Institute of Technology	Sweden
Doron Cohen	Elias	Soreq Nuclear Research Center	Israel
Sam	Emaminejad	University of California, Los Angeles	United States
Hal	Emmer	Cambridge Electronics, Inc.	United States
Sukru Burc	Eryilmaz	Stanford University	United States
David	Estrada	Boise State University	United States
Oultosin	Fawole	LivaNova	United States
Patrick	Fay	University of Notre Dame	United States
Jinjun	Feng	Beijing Vacuum Electronics Research Institute	China
Peijie	Feng	QUALCOMM Inc.	United States
Julio	Fernandez	Universidad Nacional de Educacion a Distancia	Spain
Emma	Findlay	University of Cambridge	United Kingdom
Karine	Florent	IMEC	Belgium
Kristel	Fobelets	Imperial College London	United Kingdom
Xuanyao	Fong	National University of Singapore	Singapore
Jerry	Fossum	University of Florida	United States
Aaron	Franklin	Duke University	United States
Antoine	Frappé	Yncréa HDF	France
Martin	Frey	Synopsys Switzerland LLC	Switzerland
Houqiang	Fu	Arizona State University	United States
Kai	Fu	Arizona State University	United States
Qiang	Fu	University of California, Davis	United States

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Qiuyun	Fu	Huazhong University of Science and Technology	United States
Masafumi	Fukunari	University of Fukui	Japan
Mamoru	Furuta	Kochi University of Technology	Japan
Kartik	Ganapathi	Intel	United States
Udayan	Ganguly	Indian Institute of Technology Bombay	India
Sumit	Gangwal	Lumileds	United States
Bin	Gao	Tsinghua University	China
Feng	Gao	Hong Kong University of Science and Technology	Hong Kong
Daniele	Garbin	IMEC	Belgium
Ivan	Garduño	CINVESTAV	Mexico
Kurt	Gaskill	US Naval Research Laboratory	United States
Wafaa	Gebril	University of Arkansas	United States
Frank	Geelhaar	Synopsys Inc.	United States
Alp	Gencer	Synopsys GmbH	Germany
Dimitra	Georgiadou	Imperial College London	United Kingdom
Girish	Ghivela	Visvesvaraya National Institute of Technology	India
Rocco	Giofrè	Università di Roma Tor Vergata	Italy
Bruce	Gnade	University of Texas at Dallas	United States
Antonio	Gnudi	Università di Bologna	Italy
Nanbo	Gong	Yale University	United States
Xiao	Gong	National University of Singapore	Singapore
Xiong	Gong	University of Akron	United States
Yiyang	Gong	Pennsylvania State University	United States
Saianand	Gopalan	University of Newcastle	Australia
Tetsuya	Goto	Tohoku University	Japan
Rekha	Govindaraj	University of South Florida	United States
Tibor	Grasser	Technical University of Vienna	Austria
Gerd	Grau	York University	Canada
Giuseppe	Greco	CNR-IMM	Italy
Andrew	Green	Wright-Patterson Air Force Base	United States
Alessandro	Grossi	Infineon Technologies France	France
Timothy	Grotjohn	Michigan State University	United States
Marius	Grundmann	Universität Leipzig	Germany
Yuan	Gu	University of Maryland, College Park	United States
Matthew	Guidry	University of California, Santa Barbara	United States
Fatih	Gül	Gumushane Universitesi	Turkey
Dechao	Guo	IBM Corporation	United States
Chirag	Gupta	University Of California, Santa Barbara	United States
Devki Nandan	Gupta	University of Delhi	India
Geetak	Gupta	Transphorm Inc.	United States
Sumeet	Gupta	Purdue University	United States
Jérémy	Guy	Crossbar	United States
Jaakko	Haekoenen	Ruder Boskovic Institute	Croatia
Steve	Hall	University of Liverpool	United Kingdom
Said	Hamdioui	Delft University of Technology	Netherlands
Jin-Woo	Han	NASA Ames Research Center	United States
Kijeong	Han	North Carolina State University	United States
Akito	Hara	Tohoku Gakuin University	Japan
Kenji	Hara	Hitachi Ltd.	Japan
Nazila	Haratipour	University of Minnesota	United States
Raqibul	Hasan	University of Dayton	United States
Jiabei	He	Hong Kong University of Science and Technology	Hong Kong
Yihui	He	Northwestern University	United States
Yu	He	Synopsys Inc.	United States
Dawei	Heh	Taiwan Semiconductor Manufacturing Co. Ltd.	Taiwan
Olle	Heinonen	Argonne National Laboratory	United States

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Eric	Heller	US Air Force Research Laboratory	United States
Zahra	Hemmat	University of Illinois at Chicago	United States
Francois	Henley	Tesoro Scientific, Inc.	United States
Lars	Heuken	Institut für Mikroelektronik Stuttgart (IMS-CHIPS)	Germany
Masato	Hiramatsu	Toshiba Mobile Display Co., Ltd.	Japan
Michael	Hoffmann	NaMLab GmbH	Germany
Heebum	Hong	Samsung Electronics	Korea
Naoto	Horiguchi	IMEC	Belgium
Ray-Hua	Hornng	National Chiao Tung University	Taiwan
Brian	Hoskins	National Institute of Standards and Technology	United States
Fahad	Hossain	University of California, Berkeley	United States
Shuoben	Hou	KTH Royal Institute of Technology	Sweden
Tuo-Hung	Hou	National Chiao Tung University	Taiwan
Gen-Wen	Hsieh	University of Cambridge	United Kingdom
Jie	Hu	Massachusetts Institute of Technology	United States
Shengdong	Hu	Chongqing University	China
Shiben	Hu	South China University of Technology	China
Zhaosheng	Hu	Kyushu Institute of Technology	Japan
Zhaoying	Hu	GlobalFoundries	United States
Mengyuan	Hua	Hong Kong University of Science and Technology	Hong Kong
Biqin	Huang	HRL Laboratories LLC	United States
JianJang	Huang	National Taiwan University	Taiwan
Junkai	Huang	Jinan University	China
Wei	Huang	Shanghai Institute of Ceramics, Chinese Academy of Sciences	China
Boris	Hudec	National Chiao Tung University	Taiwan
Gwendolyn	Hummel	Sandia National Laboratories	United States
Ting-Hsiang	Hung	Ohio State University	United States
Cheol Seong	Hwang	Seoul National University	Korea
Chi-Sun	Hwang	Electronics and Telecommunications Research Institute	Korea
Hyunsang	Hwang	Pohang University of Science and Technology	Korea
Keisuke	Ide	Tokyo Institute of Technology	Japan
Daniele	Ielmini	Politecnico di Milano	Italy
Hesameddin	Ilatikhameneh	Purdue University	United States
Jean Anne	Incorvia	University of Texas at Austin	United States
Koichi	Ishida	Technische Universität Dresden	Germany
Raisul	Islam	Stanford University	United States
Tony	Ivanov	US Army Research Laboratory	United States
Noriyuki	Iwamuro	Tsukuba Daigaku	Japan
S. Sundar Kumar	Iyer	Indian Institute of Technology Kanpur	India
Subramanian	Iyer	University of California, Los Angeles	United States
Warren	Jackson	Xerox Palo Alto Research Center	United States
Alfonso Torres	Jacome	INAOE	Mexico
Doyoung	Jang	IMEC	Belgium
Jaewon	Jang	Kyungpook National University	Korea
Debdeep	Jena	Cornell University	United States
Jiann-Shing	Jeng	National Tainan University	Taiwan
Jaewook	Jeong	Chungbuk National University	Korea
Matthew	Jerry	University of Notre Dame	United States
Yichen	Jia	Yale University	United States
Chao	Jiang	National Center for Nanoscience and Technology	China
Huaxing	Jiang	Hong Kong University of Science and Technology	Hong Kong
Jian-Hua	Jiang	Soochow University	United States
Lingli	Jiang	South University of Science and Technology of China	China



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Ran	Jiang	Shandong University	China
Yifan	Jiang	North Carolina State University	United States
Yonggang	Jiang	Beihang University	China
Jidong	Jin	Durham University	United Kingdom
Yufeng	Jin	Shenzhen Graduate School of Peking University	China
Ted	Johansson	Linköping University	Sweden
Nicholas	Jordan	University of Michigan	United States
Alvin	Joseph	GlobalFoundries	United States
Ravi	Joshi	Texas Tech University	United States
Sunghun	Jung	Seoul National University	Korea
Jinfeng	Kang	Peking University	China
Jong-chan	Kang	HRL Laboratories LLC	United States
Nickvash	Kani	Reservoir Labs	United States
Kuo-Hsing	Kao	Nation Cheng Kung University	Taiwan
Vural	Kara	Boston University	United States
Amanpreet	Kaur	Michigan State University	United States
Kentaro	Kawai	Osaka University	Japan
Kaveh	Khaliji	University of Minnesota, Twin Cities	United States
Asif	Khan	Georgia Institute of Technology	United States
Dong Myong	Kim	Kookmin University	Korea
Ha Sul	Kim	Chonnam National University	Korea
Hyun-Suk	Kim	Chungnam National University	Korea
June-Seo	Kim	Deagu Gyeonbuk Institute of Science & Technology	Korea
Raseong	Kim	Intel	United States
SangBum	Kim	Seoul National Univeristy	Korea
Sang-Hyeon	Kim	Korea Institute of Science and Technology	Korea
Sangwan	Kim	Ajou University	Korea
Se Kwon	Kim	University of Missouri Columbia	United States
Seong-Jin	Kim	Ulsan National Institute of Science and Technology	Korea
Taewoo	Kim	University of Ulsan	Kuwait
Mutsumi	Kimura	Ryukoku University	Japan
Michael	King	Sandia National Laboratories	United States
Isik C.	Kizilyalli	Advanced Research Projects Agency	United States
Tihomir	Knezevic	University of Zagreb	Croatia
Cagil	Koroglu	Stanford University	United States
Roza	Kotlyar	Intel	United States
Franz	Kreupl	Technische Universität Munchen	Germany
Sriram	Krishnamoorthy	University of Utah	United States
Karthik	Krishnaswamy	Intel	United States
Zoran	Krivokapic	Advanced Micro Devices Inc.	United States
Martin	Kroner	ETH Zürich	Switzerland
Valeriya	Kudina	Institute of Semiconductor Physics	Ukraine
Shin-Ichiro	Kuroki	Hiroshima University	Japan
Uihui	Kwon	Samsung Electronics	Korea
Avinash	Lahgere	Indian Institute of Technology Delhi	India
Peter	Lai	University of Hong Kong	Hong Kong
Rakesh	Lal	Transphorm Inc.	United States
William	Lambert	Intel	United States
Mario	Lanza	Soochow University	China
Alvaro	Latorre Rey	Intel	United States
Akash	Laturia	University of Texas at Dallas	United States
Tsong-Sheng	Lay	National Chung Hsing University	Taiwan
Van	Le	Intel	United States
Donguk	Lee	Pohang University of Science and Technology	Korea

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Hyeon-Jun	Lee	Deagu Gyeonbuk Institute of Science & Technology	Korea
Hyunjea	Lee	Cornell University	United States
In-Geun	Lee	Yonsei University	Korea
Jae Woo	Lee	Korea University	Korea
Kyuseok	Lee	Micron Technology	United States
Min-Hung	Lee	National Taiwan Normal University	Taiwan
Minjoo	Lee	University of Illinois at Urbana-Champaign	United States
Rinus	Lee	GlobalFoundries	United States
San-Liang	Lee	National Taiwan University of Science and Technology	Taiwan
Siwoo	Lee	Micron Technology	United States
Yao-Jen	Lee	National Nano Device Laboratories	Taiwan
Aivars	Lelis	US Army Research Lab	United States
Jori	Lemettinen	Aalto University	Finland
Pawel	Lenarczyk	ETH Zürich	Switzerland
Can	Li	University of Massachusetts	United States
Haitong	Li	Stanford University	United States
Huanglong	Li	Tsinghua University	China
Jing	Li	Xidian University	China
Ling	Li	Institute of Microelectronics, Chinese Academy of Sciences	China
Pei-Wen	Li	National Chiao Tung University	Taiwan
Pengwei	Li	Taiyuan University of Technology	China
Rui	Li	Applied Materials Inc.	United States
Rui	Li	Rutgers University	United States
Ruiping	Li	Xi'an University of Technology	China
Wei-Chang	Li	National Taiwan University	Taiwan
Wenshen	Li	Cornell University	United States
Xiang	Li	Cornell University	United States
Xiangdong	Li	Katholieke Universiteit Leuven	Belgium
Xueqing	Li	Tsinghua University	China
Zehong	Li	University of Electronic Science and Technology of China	China
Chundong	Liang	Vanderbilt University	United States
Lin	Liang	Huazhong University of Science and Technology	China
Qihua	Liang	FOM-instituut DIFFER	Netherlands
Wei	Liang	GlobalFoundries	United States
Milton	Liao	National Taiwan University	Taiwan
Min	Liao	Xiangtan University	China
Peilin	Liao	Purdue University	United States
Wen	Liao	University of Texas at Austin	United States
Rugved	Likhite	University of Utah	United States
Ee	Lim	Intel Malaysia	Malaysia
Chih-Lung	Lin	National Cheng Kung University	Taiwan
Chih-Ting	Lin	National Taiwan University	Taiwan
Richard	Lin	Synopsys Inc.	Taiwan
Yuan	Lin	University of Electronic Science and Technology of China	China
Yuxuan	Lin	Massachusetts Institute of Technology	United States
Zhiyuan	Ling	South China University of Technology	China
Juin J.	Liou	Emoat, LLC	United States
Chao	Liu	École Polytechnique Fédérale de Lausanne	Switzerland
Chee Wee	Liu	National Taiwan University	Taiwan
Chuan	Liu	Sun Yat-sen University	China
Dong	Liu	University of Wisconsin-Madison	United States



First Name	Last Name	Affiliation	Country
Gang	Liu	Ningbo Institute of Materials Technology and Engineering	China
Huichu	Liu		
Mingshan	Liu	Forschungszentrum Jülich GmbH	Germany
Qi	Liu	Institute of Microelectronics Chinese Academy of Sciences	China
Qingjun	Liu	Zhejiang University	China
Rujun	Liu	Xi'an University of Technology	China
Yang	Liu	University of Electronic Science and Technology of China	China
Yue	Liu	University of Minnesota	United States
Zheng	Liu	Nanyang Technological University	Singapore
Zhihong	Liu	Singapore-MIT Alliance for Research and Technology	Singapore
Chun-Li	Lo	Purdue University	United States
Yu-Hwa	Lo	University of California, San Diego	United States
Antonio	Lombardo	University of Cambridge	United Kingdom
Shibing	Long	Chinese Academy of Sciences	China
Nicolas	Loubet	IBM Research	United States
Tony	Low	University of Minnesota, Twin Cities	United States
Bin	Lu	Cambridge Electronics, Inc.	United States
Darsen	Lu	National Cheng Kung University	Taiwan
Ming-Pei	Lu	National Applied Research Laboratories	Taiwan
Ruochen	Lu	University of Illinois at Urbana-Champaign	United States
Shang-Chun	Lu	Massachusetts Institute of Technology	United States
Yichen	Lu	University of California, San Diego	United States
Yipeng	Lu	University of California, Davis	United States
Mathieu	Luisier	ETH Zürich	Switzerland
Fang	Luo	University of Arkansas	United States
Guang-Li	Luo	National Nano Device Laboratories	Taiwan
Jingting	Luo	Shenzhen University	China
Jun	Luo	Institute of Microelectronics, Chinese Academy of Sciences	China
Peng	Luo	University of Sheffield	United Kingdom
Xu	Luo	Micron Technology	United States
Yong	Luo	University of Tokyo	Japan
Zhengdong	Luo	University of Warwick	United Kingdom
Nicola	Lupo	Università di Pavia	Italy
Hangbing	Lv	Institute of Microelectronics, Chinese Academy of Sciences	China
Yuanjie	Lv	Shandong University	China
Alexander	Lyublinsky	Ioffe Physical-Technical Institute, RAS	
Fei	Ma	Jiaotong University	China
Jun	Ma	École Polytechnique Fédérale de Lausanne	Switzerland
Kui	Ma	University of Toronto	Canada
T. P.	Ma	Yale University	United States
William Cheng-Yu	Ma	National Sun Yat-sen University	Taiwan
Yanwen	Ma	Nanjing University of Posts and Telecommunications	China
Hiwa	Mahmoudi	Technical University of Vienna	Austria
Ivano	Maio	Politecnico di Torino	Italy
Santanu	Maity	Tezpur University School of Engineering	India
Mohamadali	Malakoutian	University of California, Davis	United States
Takashi	Manago	Fukuoka University	Japan
Meghna	Mankalale	University of Minnesota	United States

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Olivier	Marcelot	ISAE	France
Vladimir	Markevich	University of Manchester	United Kingdom
Ignacio	Martin-Bragado	Synopsys Inc.	United States
Masahiro	Masunaga	Hitachi Ltd. Central Research Laboratory	Japan
Elison	Matioli	École Polytechnique Fédérale de Lausanne	Switzerland
Jun-ichi	Matsuda	Gunma University	Japan
Makoto	Matsui	Shizuoka University	Japan
Hideaki	Matsuzaki	NTT Corporation	Japan
Alexander	Mayorov	University of Leeds	United Kingdom
Liam	McDaid	University of Ulster	United Kingdom
Nicole	McFarlane	University of Tennessee - Knoxville	United States
Cristina	Medina-Bailon	University of Glasgow	United Kingdom
Ruchit	Mehta	Western Digital Technologies Inc.	United States
Stephan	Menzel	Forschungszentrum Jülich GmbH	Germany
Wenbo	Mi	Tianjin University	China
Xiangshui	Miao	Huazhong University of Science and Technology	China
Nicholas	Miller	US Air Force Research Laboratory	United States
Jie	Min	GlobalFoundries	United States
Martin	Mitan	Intel	United States
Jérôme	Mitard	IMEC	Belgium
Naruhisa	Miura	Mitsubishi Electric Corporation	Japan
Peter	Moens	ON Semiconductor	Belgium
Ahmed	Mohamed	University of Illinois at Chicago	United States
Majid	Mohseni	Shahid Beheshti University	Iran
Daniele	Monahan	Aerospace Corp	United States
Morteza	Monavarian	University of New Mexico	United States
Udit	Monga	Samsung Electronics	Korea
Christian	Monzio Compagnoni	Politecnico di Milano	Italy
Baxter	Moody	HexaTech, Inc.	United States
Dong-Il	Moon	NASA Ames Research Center	United States
Yi-Shien	Mor	Taiwan Semiconductor Manufacturing Co. Ltd.	Taiwan
Neil	Moser	George Mason University	United States
Rouhollah	Mousavi Iraei	Georgia Institute of Technology	United States
Hema	Movva	University of Texas at Austin	United States
Robert	Mroczynski	Warsaw University of Technology	Poland
Xiaojing	Mu	Chongqing University	China
Halid	Mulaosmanovic	NaMLab gGmbH	Germany
Katsuhisa	Murakami	National Institute of Advanced Industrial Science and Technology	Japan
V. Karthik	Nagareddy	University of Exeter	United Kingdom
Takuma	Nanjo	Mitsubishi Electric Corporation	Japan
Pritish	Narayanan	IBM Research Almaden	United States
Sudarshan	Narayanan	GlobalFoundries	United States
Faouzi	Nasri	University of Monastir	Tunisia
Mihail	Nedjalkov	Technical University of Vienna	Austria
Kai	Ni	Vanderbilt University	United States
Gianluca	Nicosia	Politecnico di Milano	Italy
Magdalena	Nistor	National Institute for Laser Plasma and Radiation Physics	Romania
Akihisa	Ogino	Shizuoka University	Japan
Hyungrock	Oh	IMEC	Belgium
Saeroonter	Oh	Hanyang University	Korea
Sangheon	Oh	University of California, San Diego	United States
Shun-ichiro	Ohmi	Tokyo Institute of Technology	Japan
Aaron	Oki	Northrop Grumman Space Technology	United States
Phil	Oldiges	IBM	United States

First Name	Last Name	Affiliation	Country
Yuichi	Onozawa	Fuji Electric Co. Ltd.	Japan
Yasuhiko	Oonishi	Fuji Electric Co. Ltd.	Japan
Laurent	Osberger	Albert-Ludwigs-Universitat Freiburg Institut fur Mikrosystemtechnik	Germany
Takayoshi	Oshima	Saga University	Japan
Vaibhav	Ostwal	Purdue University	United States
Burak	Ozpineci	University of Tennessee - Knoxville	United States
Girish	Pahwa	Indian Institute of Technology Kanpur	India
Pierpaolo	Palestri	Università Degli Studi di Udine	Italy
Chenyun	Pan	University of Kansas	United States
Nikolaos	Papadopoulos	University of Waterloo	Canada
Chanho	Park	Vishay Siliconix	United States
Jaehoon	Park	Seoul National University	Korea
Jae-Woo	Park	KAIST	Korea
Jang-Ung	Park	Ulsan National Institute of Science and Technology	Korea
Jin-Hong	Park	Sungkyunkwan University	Korea
Joon-Shik	Park	Korea Electronics Technology Institute	Korea
Wanjun	Park	Hanyang University	Korea
Razvan	Pascu	National Institute for Research and Development in Microtechnologies -IMT Bucharest	Romania
Marcelo	Pavanello	Centro Universitario da FEI	Brazil
Melika	Payvand	Institut fur Neuroinformatik UZH/ETH	Switzerland
Carlos	Paz de Araujo	University of Colorado at Colorado Springs	United States
Yue	Peng	Xidian University	United States
Matteo	Perenzoni	Fondazione Bruno Kessler	Italy
Julien	Pernot	Institut Néel	France
Josh	Perozek	Massachusetts Institute of Technology	United States
Yuriy	Pershin	University of South Carolina	United States
Milan	Pešić	NaMLab GmbH	Germany
Luisa	Petti	Libera Universita di Bolzano	Italy
Martin	Pfost	Technische Universität Dortmund	Germany
Hoang-Phuong	Phan	Griffith University	Australia
Tanguy	Phulpin	Genie Electrique et Electronique de Paris	France
S.N.	Piramanayagam	Nanyang Technological University	Singapore
Brian	Poling	US Air Force Research Laboratory	United States
Chi-Sang	Poon	Massachusetts Institute of Technology	United States
Branko	Popovic	University of California, Davis	United States
Niels	Posthuma	K.U. Leuven	Belgium
Radislav	Potyrailo	GE Global Research	United States
Ghobad Behzadi	Pour	Islamic Azad University	Iran
Ali	Pourghaderi	Samsung Electronics	Korea
Amit	Prakash	Pohang University of Science and Technology	Korea
Nitin	Prasad	Indian Institute of Technology Madras	India
John	Provine	Aligned Carbon	United States
Raj	Pulugurtha	Georgia Institute of Technology	United States
Chuang	Qian	University of California, Berkeley	United States
Pedro	Quintero	Intel	United States
Janaki	Radhakrishnan	IMEC	Belgium
Mostafa	Rahimi Azghadi	University of Sydney	Australia
Munaf	Rahimo	MTAL GmbH	Switzerland
Rajib	Rahman	Purdue University	United States
Alok	Rastogi	Binghamton University	United States
Martin	Rau	ETH Zürich	Switzerland
Ali	Razavieh	GlobalFoundries	United States
Manijeh	Razeghi	Northwestern University	United States

First Name	Last Name	Affiliation	Country
Pramod	Reddy	North Carolina State University	United States
Zeyang	Ren	Xidian University	China
Andreas	Richter	Technische Universität Dresden	Germany
Rafael	Rios	Samsung	United States
Romain	Ritzenthaler	IMEC	Belgium
Antonio	Rizzo	Università di Padova	Italy
Serena	Rizzolo	ISAE-SUPAERO	France
Cedric	Rolin	IMEC	United States
Greg	Rollins	Synopsys Inc.	United States
Brian	Romanczyk	University of California, Santa Barbara	United States
Brian	Rowden	Danfoss Silicon Power US	United States
Tania	Roy	University of Central Florida	United States
Andrey	Rozhnev	Saratov National Research State University	Russia
Seung Wook	Ryu	SK-hynix	Korea
Alexei	Sadovnikov	Texas Instruments Inc.	United States
Atanu	Saha	Purdue University	United States
Samar	Saha	Prospicient Devices	United States
Chitkant	Sahu	Malaviya National Institute of Technology	India
Tomoya	Saito	Renesas Electronics Corporation	Japan
Wataru	Saito	Kyushu University	Japan
Yuta	Saito	National Institute of Advanced Industrial Science and Technology	Japan
Sayeeef	Salahuddin	University of California, Berkeley	United States
Ramon	Salazar	GlobalFoundries	United States
Arash	Salemi	Purdue University	United States
Hayder	Salman	University of Arkansas	United States
Marco	Sambi	STMicroelectronics	Italy
Saurabh	Sant	ETH Zürich	Switzerland
Biplab	Sarkar	North Carolina State University	United States
Biddut	Sarker	INFICON Inc. USA	United States
Masahiro	Sasaki	University of Tsukuba	Japan
Taketomo	Sato	Hokkaido University	Japan
Tanuj	Saxena	NXP Semiconductors	United States
William	Scheideler	Dartmouth College	United States
Alexander	Schmidt	Samsung Electronics	Korea
Uwe	Schroeder	NaMLab GmbH	Germany
Alexander	Schuchinsky	University of Liverpool	United Kingdom
David	Schwartz	PARC	United States
Fabio	Sebastiano	Delft University of Technology	Netherlands
Jung Hun	Seo	The State University of New York at Buffalo	United States
Tae-Yeon	Seong	Korea University	Korea
Andrei	Sergeev	US Army Research Laboratory	United States
Fukai	Shan	Qingdao University	China
Mohammadjavad	Sharifi	Shahid Beheshti University	Iran
Abhishek	Sharma	Intel	United States
Pankaj	Sharma	Micron Technology	United States
Guozhen	Shen	Chinese Academy of Sciences	China
Rohit	Shenoy	Intel	United States
Jinn-Kong	Sheu	National Cheng Kung University	Taiwan
Jian	Shi	Harvard University	United States
Yuhan	Shi	University of California, San Diego	United States
Lucian	Shifren	ARM	United Kingdom
Dong-Soo	Shin	Hanyang University	Korea
Keisuke	Shinohara	Teledyne Scientific and Imaging	United States

First Name	Last Name	Affiliation	Country
Alexey	Shitvov	Cardiff University	United Kingdom
Pragya	Shrestha	National Institute of Standards and Technology	United States
Mayank	Shrivastava	Indian Institute of Science	India
Pitamber	Shukla	SanDisk	United States
Nikhil	Shukla	University of Virginia	United States
Mengwei	Si	Purdue University	United States
Helena	Silva	University of Connecticut	United States
Eddy	Simoen	IMEC	Belgium
Ramendra	Singh	Indian Institute of Technology Delhi	India
Tejinder	Singh	University of Waterloo	Canada
Quentin	Smets	IMEC	Belgium
Kyung-ah	Son	HRL Laboratories LLC	United States
Bo	Song	Cornell University	United States
Jeonghwan	Song	Pohang University of Science and Technology	Korea
Woo-Bin	Song	Samsung	Korea
Yoon-Ho	Song	Electronics and Telecommunications Research Institute	Korea
Ilias	Sourikopoulos	IRCICA	France
Dencho	Spassov	Bulgarian Academy of Sciences	Bulgaria
Purushothaman	Srinivasan	GlobalFoundries	United States
Vishnu	Srivastava	CSIR-CEERI Pilani	India
Arno	Stockman	Ghent University	Belgium
Roman	Stoklas	Slovak Academy of Sciences	Slovakia
Daniele	Stradi	QuantumWise A/S	Denmark
Jérémy	Streque	Institut Jean Lamour	France
Subhali	Subhechha	IMEC	Belgium
Tomislav	Suligoj	University of Zagreb	Croatia
Charles	Sullivan	Dartmouth College	United States
Jinming	Sun	Infineon Technologies Americas Corp	United States
Keye	Sun	University of Virginia	United States
Yanming	Sun	Beihang University	United States
Zhelin	Sun	Applied Materials Inc.	United States
Zhong	Sun	Politecnica di Milano	Italy
Surajit	Sutar	IMEC	Belgium
Alexei	Svizhenko	Synopsys Inc.	United States
Brian	Swenson	Transphorm Inc.	United States
Mohd	Syamsul	Waseda Daigaku Riko Gakujutsuin	Japan
Giulia	Tagliabue	École Polytechnique Fédérale de Lausanne	Switzerland
Armin	Tajalli	University of Utah	United States
Seiji	Takahashi	Taiwan Semiconductor Manufacturing Co. Ltd.	Taiwan
Yayoi	Takamura	University of California, Davis	United States
Kiyoshi	Takeuchi	University of Tokyo	Japan
Andrea Natale	Tallarico	Università di Bologna	Italy
Shingo	Tamaru	National Institute of Advanced Industrial Science and Technology	Japan
Chuan Seng	Tan	Nanyang Technological University	Singapore
Siew Li	Tan	National University of Singapore	Singapore
Wee Chong	Tan	National University of Singapore	Singapore
Chenjie	Tang	QUALCOMM Inc.	United States
Gaofei	Tang	Hong Kong University of Science and Technology	Hong Kong
Jian-Xin	Tang	Soochow University	China
Kechao	Tang	Stanford University	United States
Weihua	Tang	Beijing University of Posts and Telecommunications	China
Wing Man	Tang	Hong Kong Polytechnic University	Hong Kong
Xiaoli	Tang	State Key Laboratory of Electronic Thin Films and Integrated Devices	China

First Name	Last Name	Affiliation	Country
Zhikai	Tang	Efficient Power Conversion Corporation	United States
Archana	Tankasala	GlobalFoundries	United States
Toru	Tanzawa	Shizuoka University	Japan
Milan	Tapajna	Institute of Electrical Engineering SAS	Slovakia
Kirsi	Tappura	VTT Technical Research Centre of Finland	Finland
Jean-Guy	Tartarin	Laboratoire d'analyse et d'architecture des Systemes	France
Daniel	Tekleab	Aptina Imaging	United States
Tomohide	Terashima	Mitsubishi Electric Corporation	Japan
Paragkumar	Thadesar	QUALCOMM Inc.	United States
Vikram	Thakar	Sand 9 Inc.	United States
Aaron	Thean	National University of Singapore	Singapore
Pengfei	Tian	Fudan University	China
Pramod	Tiwari	Indian Institute of Technology Patna	India
Cem	Tozlu	Karamanoğlu Mehmetbey University	Turkey
Renan	Trevisoli	Universidade Federal do ABC	Brazil
Tanuj	Trivedi	Intel	United States
Huynh-Bao	Trong	Taiwan Semiconductor Manufacturing Co. Ltd.	Canada
Yao-Chuan	Tsai	National Chung Hsing University	Taiwan
Jeffrey Y.	Tsao	Sandia National Laboratories	United States
Chuan-Wei	Tsou	Georgia Institute of Technology	United States
Kunio	Tsutaki	Shizuoka University Research Institute of Electronics	Japan
Takuya	Tsutsumi	NTT Corporation	Japan
Erdin	Ture	Fraunhofer Institute for Applied Solid-State Physics	Germany
Taiki	Uemura	Samsung Electronics Giheung Site	Korea
Takafumi	Uemura	Osaka University	Japan
Pramey	Upadhyaya	Purdue University	United States
Michael	Uren	University of Bristol	United Kingdom
Ilia	Valov	Forschungszentrum Jülich GmbH	Germany
Yoeri	Van De Burgt	Eindhoven University of Technology	Netherlands
Maarten	Van De Put	University of Texas at Dallas	United States
Vera	Van Treek	Infineon Technologies AG	Germany
William	Vandenbergh	University of Texas at Dallas	United States
Nilesh	Vasa	Indian Institute of Technology Madras	India
Vladislav	Vashchenko	Maxim Integrated Products Inc.	United States
Anne	Verhulst	IMEC	Belgium
Amit	Verma	Indian Institute of Technology Kanpur	India
Devin	Verreck	IMEC	Belgium
José Manuel	Vila-Fungueiriño	University of Santiago de Compostela	Spain
Jan	Voves	Czech Technical University	Czech Republic
Fujio	Wakaya	Osaka University	Japan
Qing	Wan	Nanjing University	China
Xiangjian	Wan	Nankai University	China
Danmeng	Wang	University of California, Irvine	United States
Hao (Tom)	Wang	ON Semiconductor	China
Hongjuan	Wang	Institute of Semiconductors	China
Hongxing	Wang	Xi'an Jiaotong University	China
Jinyan	Wang	Peking University	China
Jun	Wang	Hunan University	China
Kai	Wang	Southern University of Science and Technology	China
Lai	Wang	Tsinghua University	China
Lin-Lin	Wang	Fudan University	China
Panni	Wang	Hong Kong University of Science and Technology	Hong Kong
Qionghua	Wang	Beihang University	China



First Name	Last Name	Affiliation	Country
Runsheng	Wang	Peking University	China
Shicong	Wang	Micron Technology	United States
Taifang	Wang	École Polytechnique Fédérale de Lausanne	Switzerland
Wei-Hua	Wang	Academia Sinica	Taiwan
Xiaomu	Wang	Nanjing University	China
Xin Peng	Wang	Institute of Microelectronics	Singapore
Xin-feng	Wang	Xiangtan University	China
Xingsheng	Wang	Huazhong University of Science and Technology	China
Yibo	Wang	Xidian University	China
You	Wang	Beihang University	China
Zhongrui	Wang	University of Massachusetts	United States
Robin	Wanke	Max-Planck-Institut für Festkörperforschung	Germany
Morgan	Ware	University of Arkansas	United States
Shireen	Warnock	Massachusetts Institute of Technology	United States
Eliezer	Weiss	SCD – Semi-Conductor Devices	Israel
Jess	Wellendorff	Synopsys Denmark	Denmark
Thilo	Werner	CEA LETI	France
Christian	Wetzel	Rensselaer Polytechnic Institute	United States
Robert	Whitney	LPMMC	France
Stan	Williams	RStanleyWilliams Consulting	United States
Hui-Yung	Wong	San Jose State University	United States
Jiyong	Woo	Pohang University of Science and Technology	Korea
Jiyong	Woo	Arizona State University	United States
Chung-Chih	Wu	National Taiwan University	Taiwan
Ernest	Wu	IBM T.J. Watson Research Center	United States
Heng	Wu	IBM Research	United States
Huaqiang	Wu	Tsinghua University	China
Jiang	Wu	University of Electronic Science and Technology of China	China
Jin-Ming	Wu	Zhejiang University	China
Liang	Wu	City University of Hong Kong	Hong Kong
Mong-Kai	Wu	Intel	United States
Peng	Wu	Purdue University	United States
Tian-Li	Wu	National Chiao Tung University	Taiwan
Yanqing	Wu	Peking University	China
Yung-Chun	Wu	National Tsing Hua University	Taiwan
George	Xereas	McGill University	Canada
Fengnian	Xia	Yale University	United States
Qiangfei	Xia	University of Massachusetts	United States
Zhanbo	Xia	Ohio State University	United States
Patrick	Xiao	University of California, Berkeley	United States
Guohua	Xie	Wuhan University	China
Qingyun	Xie	Massachusetts Institute of Technology	United States
Huili Grace	Xing	Cornell University	United States
Weichuan	Xing	Nanyang Technological University	Singapore
Jiangtao	Xu	Tianjin University	China
Kaikai	Xu	University of Electronic Science and Technology of China	China
Ming	Xu	Xi'an University of Technology	China
Nuo	Xu	Samsung Semiconductor Inc.	United States
Nuo	Xu	University of California, Berkeley	United States
Xiaopeng	Xu	Synopsys Inc.	United States
Yaqiong	Xu	Vanderbilt University	United States
Yong	Xu	Nanjing University of Posts and Telecommunications	China
Yue	Xu	Nanjing University of Posts and Telecommunications	China

First Name	Last Name	Affiliation	Country
Ananth Saran	Yalamarthy	Stanford University	United States
Eilam	Yalon	Stanford University	United States
Hiroshi	Yamaguchi	National Institute of Advanced Industrial Science and Technology	Japan
Tomoyuki	Yamazaki	Fuji Electric Co. Ltd.	Japan
Feng	Yan	Hong Kong Polytechnic University	Hong Kong
Hongxin	Yang	Avalanche Technology	United States
Jianhua (Joshua)	Yang	University of Massachusetts	United States
Maofeng	Yang		Canada
Shu	Yang	Zhejiang University	China
Thomas	Yang	Synopsys Inc.	Taiwan
Yang	Yang	University of Technology Sydney	Australia
Yuchao	Yang	Peking University	China
Daniel	Yap	HRL Laboratories LLC	United States
Jiandong	Ye	Nanjing University	China
Ning	Ye	Western Digital Technologies Inc.	United States
Yee-Chia	Yeo	National University of Singapore	Singapore
Heyu	Yin	Michigan State University	United States
Karthik	Yogendra	IBM Research	United States
Won Jong	Yoo	Sunkyunkwan University	Korea
Youngki	Yoon	University of Waterloo	Canada
Sheng-Joue	Young	National Formosa University	Taiwan
Dong	Yu	University of California, Davis	United States
Hao	Yu	IMEC	Belgium
Hongbin	Yu	Huazhong University of Science and Technology	China
Hyun-Yong	Yu	Korea University	Korea
Shimeng	Yu	Georgia Institute of Technology	United States
Nicolò	Zagni	Università di Modena e Reggio Emilia	Italy
Peter	Zampardi	Qorvo, Inc.	United States
Ke	Zeng	University at Buffalo	United States
Anbang	Zhang	University of Electronic Science and Technology of China	China
Bo	Zhang	University of Electronic Science and Technology of China	China
Chen	Zhang	IBM	United States
Dongliang	Zhang	Shanghai Institute of Microsystem and Information Technology	China
Feng	Zhang	Purdue University	United States
Fujun	Zhang	Institute of Optoelectronic Technology	China
Han	Zhang	Shenzhen University	China
Liang	Zhang	University of Strathclyde	United Kingdom
Peng	Zhang	Michigan State University	United States
Qiaogen	Zhang	State Key Laboratory of Electrical Insulation and Power Equipment	China
Rui	Zhang	University of Tokyo	Japan
Shengdong	Zhang	Peking University	China
Shiming	Zhang	University of California, Los Angeles	United States
Wei	Zhang	Liverpool John Moores University	United Kingdom
Xinan	Zhang	Henan University	China
Xu	Zhang	Massachusetts Institute of Technology	United States
Xuchen	Zhang	Georgia Institute of Technology	United States
Yachao	Zhang	Xidian University	China
Yang	Zhang	Georgia Institute of Technology	United States
Yating	Zhang	Tianjin University	China
Yuhao	Zhang	Virginia Tech	United States

<b>First Name</b>	<b>Last Name</b>	<b>Affiliation</b>	<b>Country</b>
Zi-Hui	Zhang	Hebei University of Technology	China
Cezhou	Zhao	Xi'an Jiaotong-Liverpool Univerpool	China
Linna	Zhao	Jiangnan University	China
Lixia	Zhao	Institute of Semiconductors	China
Meixiong	Zhao	GlobalFoundries	United States
Xin	Zhao	Massachusetts Institute of Technology	United States
Xiuli	Zhao	Chengdu Institute of Organic Chemistry	China
Ying	Zhao	Institute of Microelectronics, Chinese Academy of Sciences	China
Yuji	Zhao	Arizona State University	United States
Huai	Zheng	Wuhan University	China
Jiyuan	Zheng	University of Virginia	United States
Qinghong	Zheng	Fujian Agriculture and Forestry University	China
Hong	Zhou	Xidian University	China
Jiuren	Zhou	University of California, Berkeley	United States
Peng	Zhou	Fudan University	China
Ruiping	Zhou	Purdue University	United States
Wei	Zhou	Hong Kong University of Science and Technology	Hong Kong
Yuanzhong	Zhou	Analog Devices Inc.	United States
Haoshen	Zhu	South China University of Technology	China
Mingda	Zhu	Finisar Corp	United States
Wenjuan	Zhu	University of Illinois	United States
Christian	Zorman	Case Western Reserve University	United States
Jie	Zou	University of California, Berkeley	United States
Ahmad	Zubair	Massachusetts Institute of Technology	United States
Grayson	Zulauf	Stanford University	United States